

Title (en)  
METHOD FOR CONTACTING ELECTRICAL CONTACT SURFACES OF A SUBSTRATE AND DEVICE CONSISTING OF A SUBSTRATE HAVING ELECTRICAL CONTACT SURFACES

Title (de)  
VERFAHREN ZUM KONTAKTIEREN ELEKTRISCHER KONTAKTFLÄCHEN EINES SUBSTRATS UND VORRICHTUNG AUS EINEM SUBSTRAT MIT ELEKTRISCHEN KONTAKTFLÄCHEN

Title (fr)  
PROCEDE D'ETABLISSEMENT DE CONTACT POUR DES SURFACES DE CONTACT ELECTRIQUES SITUEES SUR UN SUBSTRAT ET DISPOSITIF CONSTITUE D'UN SUBSTRAT POURVU DE SURFACES DE CONTACT ELECTRIQUES

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Application  
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Abstract (en)  
[origin: WO03030247A2] The invention relates to a method for contacting electrical contact surfaces (21, 112) on a surface (20) of a substrate (1). According to said method, a film (3) based on polyimide or epoxy is laminated onto the surface, under a vacuum, in such a way that the film closely covers the surface comprising the contact surfaces and adheres to the same. Each contact surface to be contacted on the surface is uncovered by opening respective windows (31) in the film, and a contact is established in a plane manner between each uncovered contact surface and a layer (4) of metal. The inventive method is used to establish a large-surface contact for power semiconductor chips, enabling a high current density.

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IPC 8 full level  
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CPC (source: EP KR US)  
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